

## Product Summary

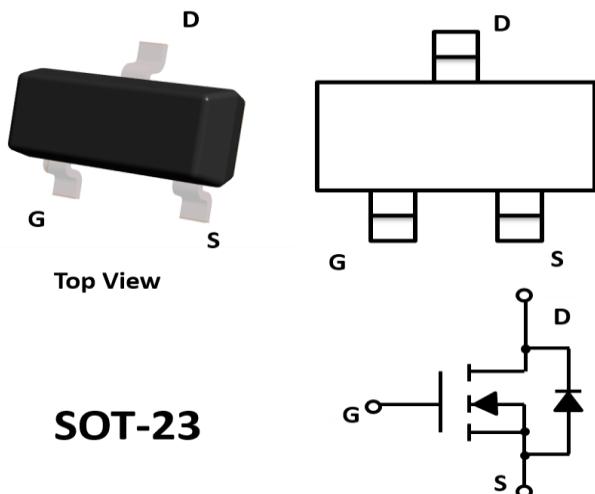
- $V_{DS}$  40V
- $I_D$  5A
- $R_{DS(ON)}$  (at  $V_{GS}=10V$ ) <45mohm
- $R_{DS(ON)}$  (at  $V_{GS}=4.5V$ ) <60mohm

## General Description

- Trench Power LV MOSFET technology
- High Power and current handing capability

## Applications

- PWM application
- Load switch



## Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	$V_{DS}$	40	V
Gate-source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current	$I_D$	5	A
		4	
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	20	A
Total Power Dissipation @ $T_A=25^\circ C$	$P_D$	1.2	W
Thermal Resistance Junction-to-Ambient @ Steady State <sup>B</sup>	$R_{\theta JA}$	104	$^\circ C / W$
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	$^\circ C$

## Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
LXN540C	F2		3000	30000	120000	7" reel

Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40			V
Zero Gate Voltage Drain Current	$I_{\text{DS}0}$	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}, T_c=25^\circ\text{C}$			1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}1}$	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
	$I_{\text{GSS}2}$	$V_{\text{GS}}= \pm 10\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 50$	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}= V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.5	2.5	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}= 10\text{V}, I_{\text{D}}=5\text{A}$		30	45	$\text{m}\Omega$
		$V_{\text{GS}}= 4.5\text{V}, I_{\text{D}}=3\text{A}$		40	60	
Diode Forward Voltage	$V_{\text{SD}}$	$I_{\text{S}}=5\text{A}, V_{\text{GS}}=0\text{V}$			1.2	V
Maximum Body-Diode Continuous Current	$I_{\text{S}}$				5	A
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		490		$\text{pF}$
Output Capacitance	$C_{\text{oss}}$			92		
Reverse Transfer Capacitance	$C_{\text{rss}}$			68		
<b>Switching Parameters</b>						
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=20\text{V}, I_{\text{D}}=3.5\text{A}$		5.2		$\text{nC}$
Gate Source Charge	$Q_{\text{gs}}$			0.9		
Gate Drain Charge	$Q_{\text{gd}}$			1.3		
Turn-on Delay Time	$t_{\text{D}(\text{on})}$	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=20\text{V}, R_{\text{L}}=2\Omega, R_{\text{GEN}}=3\Omega$		13		$\text{ns}$
Turn-on Rise Time	$t_{\text{r}}$			52		
Turn-off Delay Time	$t_{\text{D}(\text{off})}$			17		
Turn-off Fall Time	$t_{\text{f}}$			10		

A. Pulse Test: Pulse Width $\leq 300\text{us}$ , Duty cycle  $\leq 2\%$ .

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

## Typical Performance Characteristics

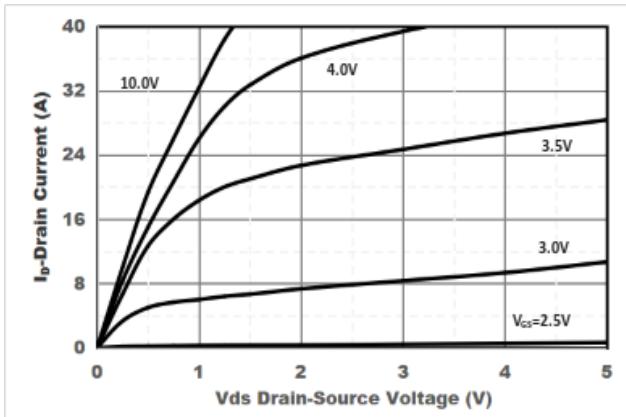


Figure 1. Output Characteristics

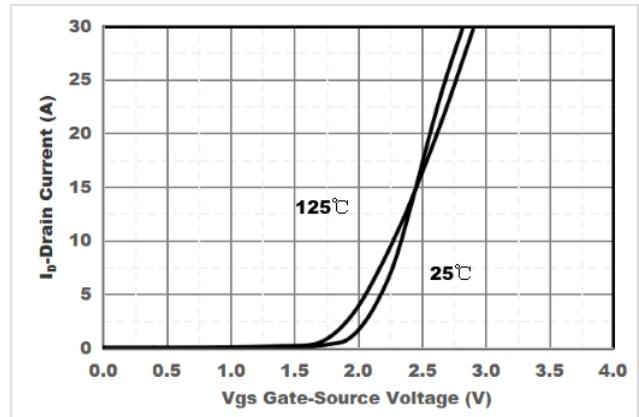


Figure 2. Transfer Characteristics

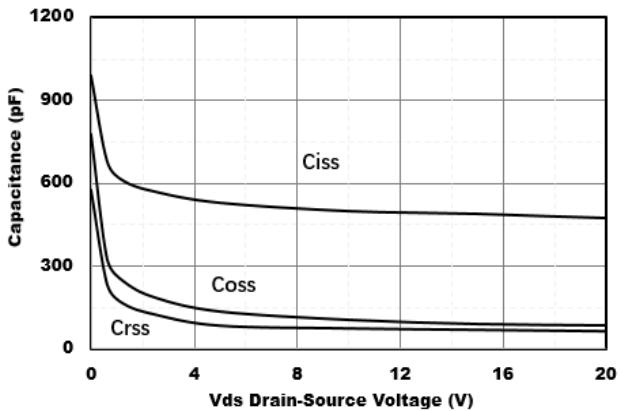


Figure 3. Capacitance Characteristics

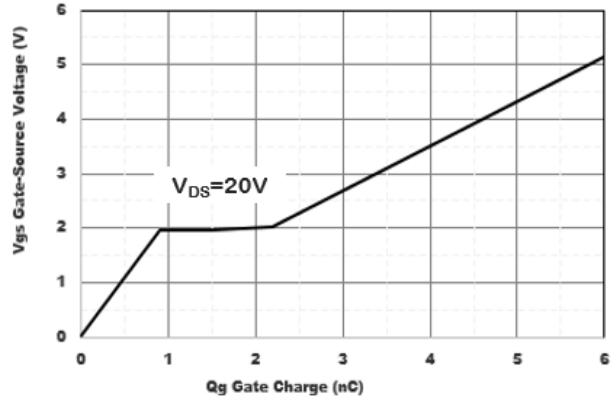


Figure 4. Gate Charge

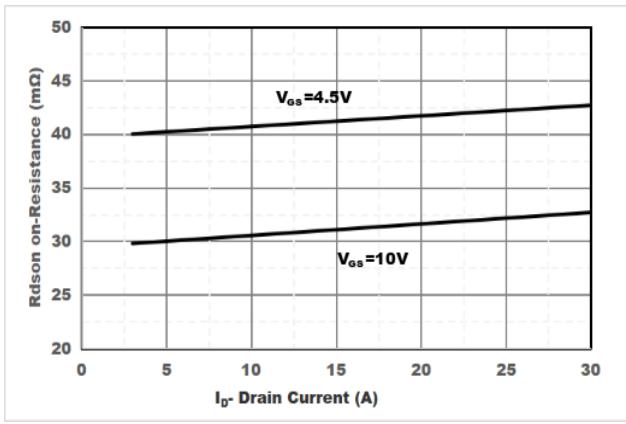


Figure 5. Drain-Source on Resistance

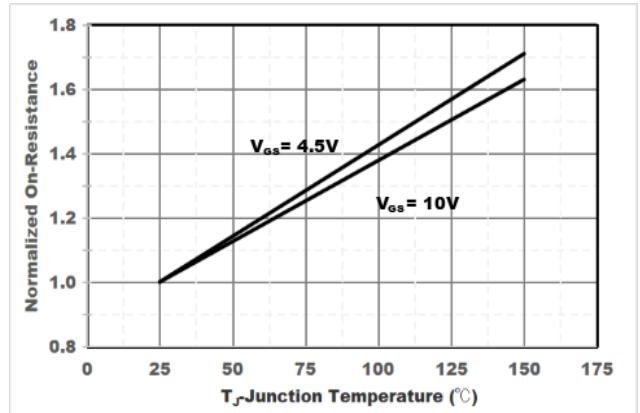


Figure 6. Drain-Source on Resistance

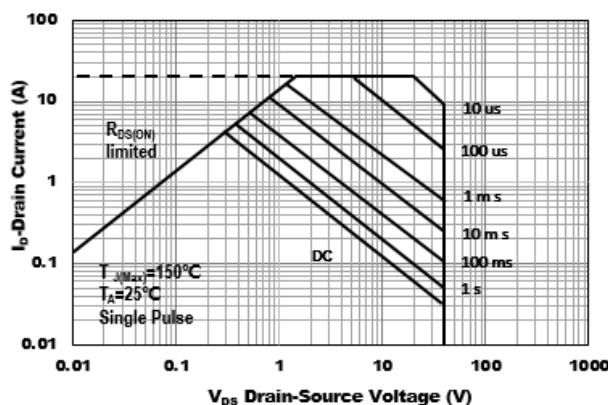


Figure 7. Safe Operation Area

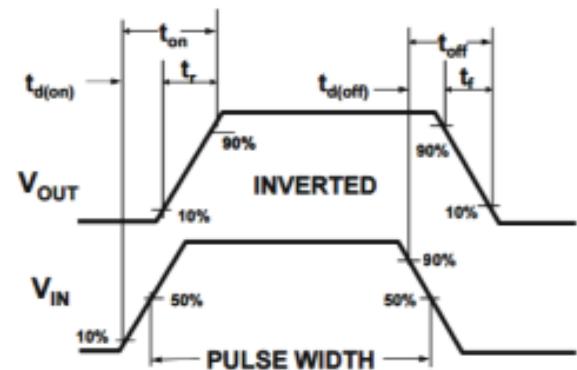
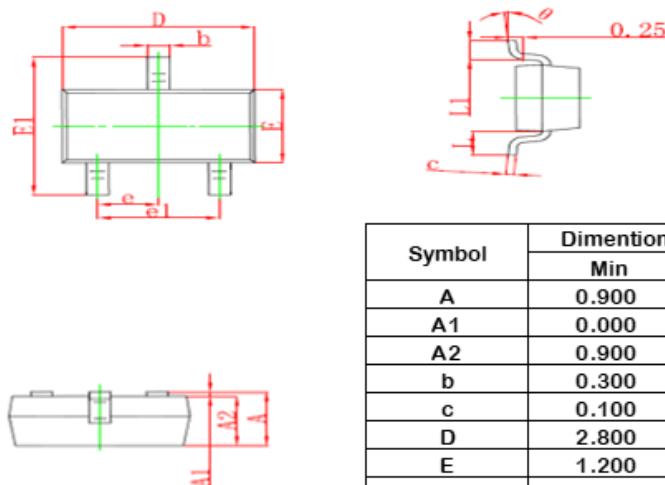


Figure 8. Switching wave

### SOT-23 Package information



Symbol	Dimensions in Millimeter		Dimensions in Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950Type		0.037Type	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.220REF	
L1	0.300	0.500	0.012	0.020
θ	0 °	8 °	0 °	8 °

### SOT-23 Suggested Pad Layout

